

## V – INFORMATION AND PARTICIPATION TO CONFERENCES AND EXHIBITIONS

### A – Annual users' meeting

The annual users' meeting, open to every person from academia or industry, using or interested in the CMP services, took place on 20 January 2011 at ASIEM – Paris (see in the Appendix 11 the list of participants).








*CMP users' meeting took place at "ASIEM" in Paris*

123 people attended the meeting coming from 78 Institutions: Academia: 80 (79 French, 1 Foreign), Industry: 43 (42 French, 1 Foreign). The following topics were presented and discussed:

#### Agenda

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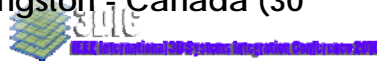
- Introduction
- General data on 2010 runs and evolution
- austriamicrosystems
  - technologies
  - high voltage CMOS, HV flash EEPROM, CMOS Opto
  - 0.18 $\mu$  HV CMOS
  - realizations in 2010
- STMicroelectronics
  - technologies
  - realizations in 2010
- Microsystems
  - technologies: MEMSCAP
  - 0.35 $\mu$  CMOS Bulk Micromachining
  - realizations in 2010
- Packaging
- Runs management and administration
- CMP checks before manufacturing
- Design kits, libraries and IPs
- Design kits and CAD tools distribution
- CIM' Alpes, CAD tools offer, Laurent FESQUET, CIME-NANOTECH 
- ARM, Eric LALARDIE, ARM
- Evatronix, Carsten ELGERT, Evatronix
- Developments in 2011
  - CMOS-magnetic 
  - Technology 3D-IC from Tezzaron 
  - Technology Fully Depleted SOI from CEA-LETI, Carlo REITA, CEA-LETI 
  - Technology AsGa TQP15 from TRIQUINT, Jean-Marie HOUILLON, TRIQUINT 
- Distributors and cooperation with other services
- Budget
- Miscellaneous

### B – Participation to conferences

In 2010, CMP organized a special session focused on the 3D-IC multi-project fabrication run being organized by CMC, CMP, MOSIS, and TEZZARON, during the IEEE International 3D Systems Conference held in Munich (Germany), 16-18 November 2010. The following topics were presented and discussed:

## Manufacturing Service on 3D ICs

- General overview/presentation, Vance TYREE, MOSIS, Marina del Rey - USA (20 mns)
- Design tools and kits, Kholdoun TORKI, CMP, Grenoble - France (15 mns)
- Testimonials and projects (25 mns):
  - \* Paul FRANZON, NCSU, Raleigh - USA (5 mns)
  - \* Gregory DEPTUCH, FERMILAB, Batavia - USA (5 mns)
  - \* Valerio RE, Univ. Bergamo - Italy (5 mns)
  - \* Jean-Claude CLEMENS, CPPM, Marseilles - France (5 mns)
  - \* Marc-André TETRAULT, Univ. Sherbrooke - Canada (5 mns)
- Discussion, Ian McWALTER, CMC, Kingston - Canada (30



In 2011, CMP is organizing a Seminar at DATE (14-18 March 2011 in Grenoble, France). The Seminar is reviewing available processes as well as recently introduced processes like 3DIC from Tezzaron, 20nm FDSOI from LETI, pHEMT GaAs from TRIQUINT. New processes will also be introduced like a magnetic-CMOS process, see agenda hereafter.

### CMP Seminar @ DATE 2011

17 March 2011 - Room Berlioz

Agenda	
09H00	Introduction, presentation of the Seminar, <i>B. COURTOIS – CMP</i>
09H10	IC processes, <i>K. TORKI - CMP</i> 1) From austriamicrosystems 2) From STMicroelectronics
09H40	MEMS processes, <i>G. DI PENDINA – CMP</i> 1) From MEMSCAP 2) From SANDIA 3) From Bulk-micromachining
09H55	Design Kits and Libraries, <i>S. DUMONT – CMP</i>
10H05	Packaging, <i>G. DI PENDINA – CMP</i>
10H15	Distribution of Design Kits, <i>S. EYRAUD - CMP</i>
10H25	Checking before manufacturing, <i>G. DI PENDINA – CMP</i>
10H35	IPs 1) Overview, <i>R. VERLY – CMP</i> 2) ARM tools and cores, <i>E. LALARDIE – ARM</i> 3) EVATRONIX IPs, <i>C. ELGERT – EVATRONIX</i>
11H00	Coffee break
11H20	New processes in 2011
11H20	1) 3D ▶ 130nm 3D-IC process from TEZZARON, <i>K. TORKI – CMP</i> ▶ 3D tools, <i>P. DOS SANTOS, J.F. LEPERE – CADENCE</i>
11H40	2) 20nm FDSOI from CEA-LETI, <i>C. REITA – CEA-LETI</i>
11H50	3) 150nm GaAs from TRIQUINT, <i>S. DUMAY – TRIQUINT</i>
12H00	4) Magnetic-CMOS circuits, <i>K. TORKI – CMP</i>
12H10	5) Powering ICs and MEMS with PV/OPV, <i>G. DI PENDINA – CMP, C. LANDROCK – I/D/ME</i>
12H20	Conclusions, other developments to be announced in 2011, discussion, <i>B. COURTOIS – CMP</i>



## C – Participation to exhibitions

CMP presented its activities on a booth at the following conferences/exhibitions in 2010:

- ▶ DESIGNCON 2 - 3 February 2010 Santa Clara - USA
- ▶ DATE 8 - 12 March 2010 Dresden - Germany
- ▶ DTIP 5 - 7 May 2010 Seville - Spain
- ▶ DAC 13 - 18 June 2010 Anaheim - USA

CMP will present its activities on a booth at the following conferences/exhibitions in 2011:

- ▶ VLSI Design 4-5-6 January 2011 Chennai, India
- ▶ DESIGNCON 2 - 3 February 2011 Santa Clara - USA
- ▶ DATE 14-18 March 2011 Grenoble - France
- ▶ DTIP 11-13 May 2011 Aix-en-Provence - France
- ▶ DAC 6-8 June 2011 San Diego - USA



*DATE 2010*



*DAC 2010*




*DESIGNCON 2010*



*VLSI Design 2011*

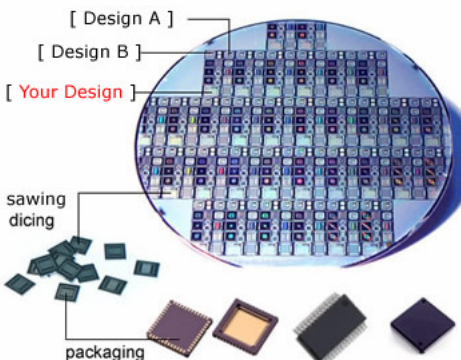
## D – Information on the WEB

The CMP Web site (<http://cmp.imag.fr>) includes all the basic information about the service.



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**CMP** is a service organization in ICs and MEMS for prototyping and low volume production. Circuits are fabricated for Universities, Research Laboratories and Industrial companies.

Advanced industrial technologies are available in CMOS, BiCMOS, SiGe BiCMOS, P-HEMT E/D GaAs, etc. CMP distributes and supports several CAD software tools for both Industrial Companies and Universities.

Since 1981 more than 4800 circuits for Research, Education and Industry have been fabricated. 850 academic centres and 150 industrial companies from 70 countries have been served.

**News & Events**

**The annual CMP users meeting will take place on 20 January 2011 in Paris.**

Agenda ([English](#), [French](#)) | [Registration](#)

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Lastest News

- 65nm PDK for Tanner Tools available from CMP
- STMicroelectronics : hcm0s9/bicmos9mw runs are scheduled
- Special Session at the 3DIC Conference: Manufacturing Service on 3D ICs

Recent Press Articles

- Evatronic and CMP collaborate to provide Universities and Research Laboratories with advanced IPs (EETimes Europe), 02 Feb 2010 (London) [Read more](#)
- ST brings CMOS process program to Chinese universities (EETimes Asia, 03 Jun 2008 [Read more](#)
- STMicroelectronics and CMP to offer CMOS processes to Chinese universities (CBROnline), 03 Jun 2008 [Read more](#)

Next Exhibitions

- [DesignCon](#) 01-02 Feb 2011 Santa Clara, USA
- [DATE](#) 14-18 Mar 2011 Grenoble, France
- [DAC](#) 05-10 Jun 2011 San Diego, USA

**Quick References**




- [Process Technology portfolio](#)
- [MPW runs schedule & Price list](#)
- [Design-kits request form](#)
- [Packaging list and prices](#)


**Upcoming Runs**

- M03S11\_1, 18 Jan 2011
- A35V11\_1, 11 Feb 2011
- A35C11\_1, 14 Feb 2011
- A35O11\_1, 14 Feb 2011
- S40C11\_1, 16 Feb 2011
- A35S11\_1, 25 Feb 2011
- A35R11\_1, 25 Feb 2011
- M08M11\_1, 08 Mar 2011
- S40C11\_2, 23 Mar 2011
- S65C11\_1, 28 Mar 2011
- M02P11\_2, 05 Apr 2011
- S13C11\_2, 13 Apr 2011
- S13S11\_2, 13 Apr 2011
- S13I11\_2, 13 Apr 2011
- M03S11\_2, 19 Apr 2011


**Customers Access**

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Current Visitors Online: 8



It includes in particular:

- ▶ **Home:** general information and a quick references section is available to help you to access to different sections (ex.: MPW runs schedule, prices, etc.)
- ▶ **About Us:** lot of information like flyer, press articles, exhibitions, annual report, slides presented to the annual users meeting and ICs examples (examples of manufactured circuits)
- ▶ **News:** last CMP news information written in the Web site

► **Products:** this part describes the different services (manufacturing, packaging, design kits, CAD Tools, etc.) with all the necessary information to participate. An overview of the different technologies is in the appendix 1

► **Submission:** procedure to submit a circuit to a CMP run

► **Documents:** order forms, packaging including price list and leadframe diagrams

► **Media coverage:** interviews (videos) and press articles

► **Contacts:** email address, phone number and biographies of staff members

► **Conferences:** a list of upcoming or past conferences organised or co-organised by CMP from 1995

Through a personalized interface, each user has its own account at CMP to receive transfer procedure, information on his circuits, files to upload or download, etc.

Customers Home

**CMP Customers interface**

**IMPORTANT:** You can use the same login and password to track the status of your submissions.

**How to use this interface**

Using this private website allows you to transfer files (menu "upload" and "download"). You also have a follow-up of your runs (menu "My Runs")

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## E – Announcements and Press articles

See in the Appendix 12 the following announcements:

- CMP chooses I|D|ME Organic Solar Cell Technology for Integration with CMOS
- CMP chooses TriQuint as its Gallium Arsenide Foundry Services Partner
- CEA-LETI makes a R&D 20nm Fully Depleted SOI process available through CMP
- CMP partners with CMC and MOSIS to introduce a 3D-IC process
- 65nm PDK for Tanner Tools available from CMP
- Evatronix and CMP collaborate to provide Universities and Research Laboratories with advanced IPs.
- CMP introducing CMOS 0.35 $\mu$  Bulk Micromachining MEMS
- Come and see us at VLSI Design 2011
- Come and see us at DesignCon 2011
- Come and see us at DAC 2010

and in Appendix 15 the CMP Press articles 2009-2010.